L Number	Hits	Search Text	DB	Time stamp
-	28	"5608257"	USPAT	2004/09/22 14:56
-	2	"63122150"	EPO; JPO; DERWENT; IBM_TDB	2004/03/31 16:51
-	6	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and (al or aluminum) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:20
-	6	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/31 17:00
-	15	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:20
-	9	((chip or die or ic or (integrated adj circuit)) and (fuse with cuttable)) not ((chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/31 16:56
-	8	(chip or die or ic or (integrated adj circuit)) and (fuse same cuttable) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/31 17:05
-	2	((chip or die or ic or (integrated adj circuit)) and (fuse same cuttable) and substrate) not ((chip or die or ic or (integrated adj circuit)) and (fuse with cuttable))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/31 17:00
-	13122	(chip or die or ic or (integrated adj circuit)) and fuse and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/31 17:07
-	427	((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:20
-	241	(((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)) and cut$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:20
-	1	(chip or die or ic or (integrated adj circuit)) and ((fuse or member or section) with cuttable) and (logic with series)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:07
-	4	(chip or die or ic or (integrated adj circuit)) and ((fuse or member or section) with cuttable) and (logic SAME series)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:07
-	7	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable) and (al or aluminum) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:20
-	16	(chip or die or ic or (integrated adj circuit)) and (fuse with cuttable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:20

-	267	(((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)) and cut$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:20
-	469	((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:21
-	146	((((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)) and cut$5) and logic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:21
-	218	(((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)) and logic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:23
-	157	((((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)) and logic) and series	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:23
-	107	(((((chip or die or ic or (integrated adj circuit)) and fuse and substrate) and (bonding adj pad)) and cut$5) and logic) and series	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:29
-	375	257/665.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:49
-	375	257/528.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:50
-	734	257/529.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:50
-	1324	257/777.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 17:31
-	1762	257/784.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:50
-	1607	257/786.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 17:31
-	1192	257/777.ccls. not 257/784.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 17:31
-	1553	257/786.ccls. not (257/777.ccls. not 257/784.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 17:31